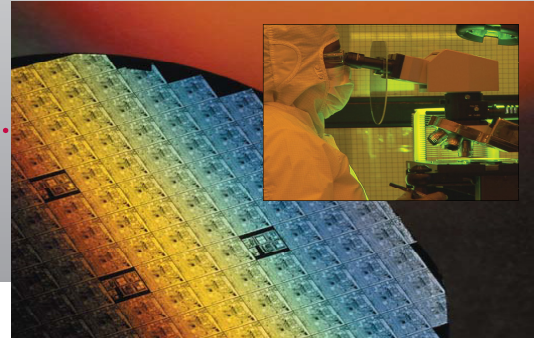


Intersil Commercial Lab Services

Intersil now offers its impressive array of Probe, Assembly and Test services to the Military and SPACE community.



Qualifications:

- Defense Logistics Agency qualified manufacturer certified to MIL-PRF-38535 for class B, Q, S, T, and V products.
- All quality conformance testing under Group A, B, C, D and E requirements, including low dose rate irradiation testing (ELDRS).
- Full ISO 9001:2008 certification
- Commercial Lab Suitability Certification for Probe, Assembly and Test

Contract Commercial Lab Services:

Access to the Intersil Commercial Lab by outside customers is provided under contract including terms and conditions. To support this service, Intersil uses guidelines based on the requirements of MIL-STD-883, ASTM F1892 and ESA specification 22900. All Commercial Lab services will be performed under a nondisclosure agreement (NDA) as a part of the contract. Any ITAR or other security restrictions must be resolved before a contract is entered into. Intersil has an on-site ITAR compliance officer.

Lab Services Plan:

The customer will generate a lab services plan, based on Intersil guidance, that will document and detail the elements of this plan. Given the wide variety of services offered, Intersil will not provide prices without an RFQ.

Package Assembly Capabilities:

Package Style	Seal Technology	Die Attach	Lead Finish	Pin Count Min/Max
Side Braze Dip	Solder Seal	Gold Eutectic, Silver Glass, Silver Polymer	Gold, Solder	8 Lead / 48 Lead
Cerdip	Glass Frit	Gold Eutectic, Silver Glass	Solder	14 Lead / 28 Lead
CPGA	Solder Seal	Gold Eutectic, Silver Glass, Silver Polymer	Gold	48 Lead / 121 Lead
CLCC	Solder Seal	Gold Eutectic, Silver Glass, Silver Polymer	Gold, Solder	8 Lead / 68 Lead
Ceramic Flat Pack	Solder Seal	Gold Eutectic, Silver Glass, Silver Polymer	Gold	8 Lead / 42 Lead
Ceramic Quad Flat Pack	Solder Seal	Gold Eutectic, Silver Glass, Silver Polymer	Gold	48 Lead / 84 Lead
Metal Can	Weld	Gold Eutectic, Silver Glass	Gold, Solder	2 Lead / 12 Lead
TO-257	Seam Weld	Solder, Silver Glass	Gold	3 Lead / 7 Lead
SMD .5	Seam Weld	Solder, Gold Eutectic	Gold	3 Lead

Package Test Capabilities:

TEST	METHOD	TEST	METHOD
Wafer Lot Acceptance	5007	Solderability	2003
SEM	2018	Lead Integrity	2004
Non-Destruct Bond-Pull	2023	Lid Torque	2024
Internal Visual	2010	Steady State Life Test	1005
Temperature Cycling	1010	Moisture Resistance	1004
Constant Acceleration	2001	Salt Atmosphere	1009
Particle Impact Noise Detection	2020	Thermal Shock	1011
Seal (Fine and Gross)	1014	Mechanical Shock	2002
Electrical Test Parameters	**	Vibration, Variable Freq.	2007
Burn-In Test	1015	Adhesion of Lead Finish	2025
Radiography	2012	Die Shear	2019/2027
External Visual	2009	Steady State Total Dose Irradiation	1019
Physical Dimensions	2016	Glassivation Layer Integrity	2021
Resistance to Solvents	2015	Terminal Capacitance	3021
Internal Visual for DPA (Destruct Physical Analysis)	2013	Electrical Discharge Sensitivity	3015
Bond Strength	2011		

** Applicable Device Specification

Wafer Probe and Package Test Platforms:

- Agilent
- LTX
- Teradyne
- TEL
- KLA

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